EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	("6159873").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/03 05:43
L2	2	("6159837").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/03 05:46
L3	2	("6107164").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/03 06:03
L4	2	("6278192").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/03 06:07
L5	2	("6153448").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/03/03 06:07
L6	42	("4904610" | "5393706" | "5445559" | "5516728" | "5527744" | "5605489" | "5888883").PN. OR ("6107164"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/03 06:34
L7	7	L6 and @ay<="1999"	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/03 07:19
L8	5	("4541000"|"4722130"|"5977641"|"6107164"|"6881611").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/03/03 07:19
S1	403	@ad<= "19991215" and (438/113-114).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:56
S2	1895	@ad<= "19991215" and (438/459-464).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:11

S4	432	@ad<= "19991215" and (438/631). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:12
S5	197	@ad<= "19991215" and (438/690). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:12
S6	138	@ad<= "19991215" and (438/33). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:12
S7	4	(("6297560") or ("6083811")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/30 16:16
S8	2	"20040099937"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:16
S9	104	@ad<= "19991215" and (438/759). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/30 16:16
S10	70	@ad<= "19991215" and (438/411). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:24
S11	187	@ad<= "19991215" and (438/461). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:24
S12	175	@ad<= "19991215" and (438/611). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:24
S13	408	@ad<= "19991215" and (438/613). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:24

S14	104	'chip' with 'size' with packag$3 and 'hitherto'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:41
S16	10	(("6060373") or ("6083811") or ("6159837") or ("6297560") or ("6590257")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/01/31 09:34
S17	2	"20020030258"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:34
S18	37	@ad<="19991215" and 'chip' with 'size' with packag$3 and 'hitherto'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 10:02
S19	1	"6159837".PN.	USPAT; USOCR	OR	ON	2006/01/31 09:42
S20	1	"6060373".PN.	USPAT; USOCR	OR	ON	2006/01/31 09:42
S21	15	@ad<="19991215" and 'chip' with 'size' with packag$3 same 'wafer' with 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:10
S22	1497	@ad<= "19991215" and (438/106).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:57
S23	486	@ad<= "19991215" and (438/107).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:57
S24	335	@ad<= "19991215" and (438/108).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 09:57
S25	1	"5943591".PN.	USPAT; USOCR	OR	ON	2006/01/31 10:02
S28	5	@ad<="19991215" and 'chip size package' and 'silicon wafer' with 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:38

S29	2	@ad<="19991215" and 'flip chip' and 'silicon wafer' with 'thickness' and 'sealing resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:18
S30	378	@ad<="19991215" and 'flip chip' and 'sealing resin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:18
S31	241	@ad<="19991215" and 'flip chip' and 'sealing resin' and 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:18
S32	154	@ad<="19991215" and 'flip chip' and 'sealing resin' same 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:20
S33	47	@ad<="19991215" and 'chip size package' and 'sealing resin' same 'bump'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:21
S34	240	@ad<="19991215" and 'silicon wafer' with 'thickness' with '200'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:40
S35	1	@ad<="19991215" and 'silicon wafer' with 'thickness' with '200' and ('BGA' or 'CSP')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:42
S36	11	@ad<="19991215" and 'thickness' same 'silicon' with '200' and ('BGA' or 'CSP')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:49
S37	12	@ad<="19991215" and 'thickness' same 'silicon' with '200' and ('BGA' or 'CSP' or 'chip scale packages' or 'chip-size packages')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:54
S38	18	@ad<="19991215" and 'silicon' with 'substrate' with '200' and ('BGA' or 'CSP' or 'chip scale packages' or 'chip-size packages')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/31 10:57
S39	45	@ad<="19991215" and 'silicon' with 'substrate' with 'thickness' and ('BGA' or 'CSP' or 'chip scale packages' or 'chip-size packages')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 10:15

S40	4	(("6680535") or ("6613694") or ("6476501")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/05/09 18:11
S42	32	@ad<="19991215" and "hitherto" and "CSP"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 10:02
S43	1	"6063646".PN.	USPAT; USOCR	OR	ON	2006/07/06 10:03
S44	1	"5851845".PN.	USPAT; USOCR	OR	ON	2006/07/06 10:13
S45	45	@ad<="19991215" and silicon with substrate with thickness and ("BGA" or "CSP" or "chip scale packages" or "chip-size packages")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 10:16
S47	1501	@ad<="19991215" and thin$4 with (silicon or wafer) and (resin or sealant) with thick$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 10:18
S49	152	@ad<="19991215" and thin$4 with (silicon or wafer) same (resin or sealant or adhesive) with thick	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 10:39
S50	1	"6051877".PN.	USPAT; USOCR	OR	ON	2006/07/06 10:23
S51	1	"5969945".PN.	USPAT; USOCR	OR	ON	2006/07/06 10:23
S52	1	"5907477".PN.	USPAT; USOCR	OR	ON	2006/07/06 10:23
S53	592	@ad<="19991215" and thin$4 same (silicon or wafer) same substrate and (resin or sealant or adhesive) with thick	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:02
S55	572	@ad<="19991215" and chip with thin$4 same (resin or sealant or adhesive) same package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 10:46
S56	6	(("5601678") or ("5620795") or ("5143785")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/06 10:47

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S57	76	@ad<="19991215" and thinning same substrate and (resin or sealant or adhesive) with thick	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:09
S58	282	@ad<="19991215" and thinning same substrate and (resin or sealant or adhesive) and package	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:17
S59	15	@ad<="19991215" and "chip" with "size" with packag$3 same "'wafer" with thick$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/06 11:11
S60	6	(("5,604,160") or ("5,798,557") or ("5,851,845")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/07/06 11:18
S61	1	"5969945".PN.	USPAT; USOCR	OR	ON	2006/07/06 11:19
S62	1	"5907477".PN.	USPAT; USOCR	OR	ON	2006/07/06 11:19
S63	1	"5805424".PN.	USPAT; USOCR	OR	ON	2006/07/06 11:19